

RELIABILITY REPORT





NOW PART OF



Reliability Data Report

Product Family R308

LT1175

Reliability Data Report

Report Number: R308

Report generated on: Mon Mar 05 10:47:41 PST 2018

OPERATING LIFE TEST					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS (+125°C) ¹	No. of FAILURES ^{2,3}
SOIC/MSOP	727	9513	1630	604	0
Totals	727	-	-	604	0

PRESSURE COOKER TEST AT 15 PSIG , +121 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
DD PAK	875	9638	1710	21	0
PLASTIC DIP	50	9603	9603	1	0
SOIC/MSOP	750	9615	1701	33	0
SOT	2275	9906	1647	102	0
TO-220	350	9534	0114	9	0
Totals	4,300	-	-	166	0

TEMP CYCLE FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
DD PAK	2300	9631	1546	230	0
SOIC/MSOP	650	9637	1701	65	0
SOT	500	9616	1647	50	0
TO-220	300	9534	0122	35	0
Totals	3,750	-	-	380	0

THERMAL SHOCK FROM -65 TO 150 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE CYCLES	No. of FAILURES
DD PAK	747	9631	1710	74	0
SOIC/MSOP	600	9947	1701	60	0
SOT	449	9906	1647	44	0
TO-220	250	9611	0829	25	0
Totals	2,046	-	-	203	0

HIGH TEMPERATURE BAKE AT 175 DEG C					
PACKAGE TYPE	SAMPLE SIZE	OLDEST DATE CODE	NEWEST DATE CODE	K DEVICE HRS	No. of FAILURES
DD PAK	50	1004	1004	50	0
SOIC/MSOP	100	1452	1701	50	0
Totals	150	-	-	100	0

(1) Assumes Activation Energy = 1.0 Electron Volts
(2) Failure Rate Equivalent to +55 °C, 60% Confidence Level =3.04 FITS
(3) Mean Time Between Failure in Years = 37611.75
Note: 1 FIT = 1 Failure in One Billion Hours.
Note 2: HAST, Temp Cycle & Thermal Shock are subjected to J-STD-020 MSL1 Preconditioning